

**2018 International Symposium on Semiconductor Manufacturing Intelligence (ISMI2018)
& 2018 IEEE International Conference on Smart Manufacturing, Industrial & Logistics
Engineering (IEEE SMILE 2018)**

Conference Chairs: Chen-Fu Chien, Jei-Zheng Wu, & Runliang Dou

February 7 - 9, 2018, Hsinchu, Taiwan

Aims and Topics:

The joint conference of 2018 International Symposium on Semiconductor Manufacturing Intelligence (ISMI2018) and 2018 IEEE International Conference on Smart Manufacturing, Industrial & Logistics Engineering (SMILE 2018) aims to disseminate recent theoretical and methodological developments, applications, and case studies in light of ongoing revolutions for manufacturing intelligence and smart manufacturing. **Topics of interest include, but are not limited to, the following:**

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| Big Data Analytics & Data Mining for Smart Manufacturing | Industry 4.0 & Cyber-Physical Systems |
| AI & Computational Intelligence for Smart Manufacturing | Advanced Process Control/ Advanced Equipment Control |
| Internet of Things (IOT) | Virtual Metrology, Tool Health, Fault Detection & Classification |
| Manufacturing Intelligence, Evolutionary Algorithms | Circular Economics, Green Supply Chain & Sustainability |
| Decision Technologies, Modeling & Decision Analysis | Augmented Reality, Virtual Reality |
| Simulation Optimization & Applications | Manufacturing Strategy & Manufacturing Innovation |
| Corporate Resource Planning & ERP | User Experience & Innovative Design |
| Smart Production Facilities & Green Fab | Human-machine Collaboration, Ergonomics & Safety |
| Predictive Maintenance, Quality & Reliability | Total Resource Management & Overall Resource Effectiveness |
| Semiconductor & High-tech Manufacturing | Applications of Industrial Engineering & Logistics |

Organized/sponsored by:

NTHU-TSMC Center for Manufacturing Excellence, National Tsing Hua University
Industrial Engineering and Management Program, Ministry of Science and Technology, Taiwan
Society for Excelling Enterprises and Decisions (SEED), Taiwan

Paper submission:

All papers must be written in English with a maximum length of 6 pages. Paper format, submission, and related information is updated: <http://DALab.ie.nthu.edu.tw/ISMI2018/> and submission page: <https://www.easychair.org/conferences/?conf=ismi2018>
For more details, please consult Co-Chair, Professor Jei-Zheng Wu (jzwu@scu.edu.tw).

Special Issues for Post-Conference Publication:

Conference proceedings of full papers will be published by IEEE Xplore that is indexed by Ei Compendex. Selected papers will be recommended for reviews and possible publications in special issues of SCI journals including Journal of Intelligent Manufacturing and others as in <http://DALab.ie.nthu.edu.tw/ISMI2018/>

Important Dates:

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| Deadline for Submission of Abstract and Special Session Proposals: | October 31, 2017 |
| Deadline for Full Paper Submission for EI Indexed Proceedings for IEEE Xplore: | October 31, 2017 |
| Deadline for Full Paper/Presentation-only Abstract Submission: | November 30, 2017 |
| Camera Ready Manuscript Submission: | January 5, 2018 |

Registration Fee:

Full registration: **US\$500** (Early bird, before December 10, 2017) / **US\$600** (Regular)
Student registration: **US\$350** (Early bird, before December 30, 2017) / **US\$400** (Regular)

Tutorial Session, Exhibit, and Factory Visiting:

This conference will provide a platform for related activities such as tutorial, exhibit, and factory visiting to enrich conference.

Venue: National Tsing Hua University (<http://nthu-en.web.nthu.edu.tw/bin/home.php>) (special offers of NTHU guest house and hotels nearby are available; visitor guide will be provided in advance for visiting Taiwan and local tours).

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